# **Higher Speed Ethernet Consensus**

Industry Connections (Individual Process)
Activity Initiation Document
Version: 1.0, 1 June 2012

#### [[Instructions

- Note: Any text surrounded by double square brackets [[]] should be replaced appropriately (and the brackets removed) in the final document, or may be deleted if so allowed. These instructions may be deleted.
- The version number above, along with the date, may be used to distinguish successive updates of the document. The file name associated with the document should also be updated accordingly.
- The status should indicate "Draft", "For Member Approval", "For Sponsor/SASB Approval", or "Approved", as appropriate.
- The Name of New IC Activity and Version information provided above will automatically update the corresponding page headers and footers (upon printing or print preview). However, the font and size of the substituted text in the headers and footers may need to be manually corrected.]

### 1. Background and Purpose

[[Briefly explain the motivation behind starting this IC activity, and the overall purpose or goal to be accomplished. Include a comparison to any existing, related efforts (industry associations, consortia, standardization activities, etc.), or existing, related standards.

• If an existing related standard has been identified and the Sponsor is still active, its name [[SponsorName]] shall be entered below. Prior to the approval of the start of the activity, approval from that Sponsor shall be obtained.]]

The completion of the IEEE 802.3 Industry Connections Ethernet Bandwidth Assessment Ad hoc has demonstrated that the bandwidth requirements of multiple application spaces are continuing an exponential climb with the forecasted growth in 2020 to reach a level 100x the bandwidth required in 2010. The purpose of the Industry Connection's Higher Speed Ethernet Consensus activity will be to build consensus related to initiating a new effort targeting the next speed of Ethernet for wireline applications, which will be used for the evaluation and possible development of a Call-For-Interest for the next Higher Speed Study Group.

Related Standards – IEEE Std 802.3-2008 and IEEE Std 802.3ba-2010 Related Sponsor – IEEE 802

#### 2. Charter and Scope

Within the IEEE Standards Association (IEEE-SA), the Higher Speed Ethernet Consensus activity will be overseen by the IEEE-SA Standards Board (SASB) Industry Connections Committee (ICCom), and IEEE 802. The charter of Higher Speed Ethernet Consensus focuses its activities as follows:

• [[Through a series of points or sentences, outline what types of work will be undertaken by this IC activity, clarifying what is in (and what is out of) scope.]]

The scope of this IC activity will focus on building consensus related to the next speed of Ethernet for wireline applications, which will be used for the evaluation and possible development of a Call-For-Interest for the next Higher Speed Study Group.

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### 3. Potential Markets Served

[[Indicate the main beneficiaries of this work, and what the potential impact might be. This is an optional section that may be omitted if already covered under Background and Purpose.]]

The potential beneficiaries of this work would be those individuals involved in future Ethernet wireline standards targeting higher speeds than those that currently exist. The beneficiaries of these efforts identified to date are expected to include but are not limited to: users and producers of systems and components for servers, network storage, networking systems, high performance computing, telecommunications carriers, internet exchanges, financial markets, data centers, and multiple system operators (MSOs).

## 4. Proposed Deliverables

[[Outline the anticipated deliverables and output from this IC activity, such as documents, proposals for standards, conferences and workshops, databases, computer code, etc.]]

The proposed deliverables will be the historical records, i.e. meeting notes & presentations, of the meetings held by this Industry Connections activity.

#### 5. Funding Requirements

[[Outline any additional contracted services or other expenses that are currently anticipated, beyond the basic support services provided to all IC activities.]]

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## 6. Initial Members

[[Indicate the stakeholders that are expected to be interested in this IC activity, and provide a list of the initial members (below) that will be participating from the outset. It is recommended there be at least five initial members, each with a different affiliation.]]

The initial members in Higher Speed Ethernet Consensus are the following:

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## **Revision History:**

Revision Number	Author/Editor	Date
0.1 (Draft)	John D'Ambrosia	03 Apr 2012
0.2 (Draft)	James Wendorf (IEEE)	18 Apr 2012
0.3 (Draft)	John D'Ambrosia	01 May 2012
1.0	John D'Ambrosia	01 June 2012